



Material Content Data Sheet



Sales Product Name		BTS244Z E3043		Issued		22. January 2018		
MA#		MA001225872						
Package		PG-TO220-5-12		Weight*		2124.61 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	8.082	0.38	0.38	3804	3804
leadframe	non noble metal	iron	7439-89-6	0.923	0.04		434	
	inorganic material	phosphorus	7723-14-0	0.277	0.01		130	
	non noble metal	copper	7440-50-8	921.567	43.38	43.43	433757	434321
wire	non noble metal	aluminium	7429-90-5	1.700	0.08	0.08	800	800
encapsulation	organic material	carbon black	1333-86-4	8.533	0.40		4016	
	plastics	epoxy resin	-	93.864	4.42		44179	
	inorganic material	silicondioxide	60676-86-0	466.474	21.96	26.78	219558	267753
leadfinish	non noble metal	tin	7440-31-5	24.181	1.14	1.14	11382	11382
plating	inorganic material	phosphorus	7723-14-0	0.008	0.00		4	
	non noble metal	nickel	7440-02-0	3.285	0.15	0.15	1546	1550
glue	plastics	Polyimide	26023-21-2	0.157	0.01	0.01	74	74
solder	noble metal	silver	7440-22-4	0.133	0.01		63	
	non noble metal	tin	7440-31-5	0.107	0.00		50	
	non noble metal	lead	7439-92-1	5.088	0.24	0.25	2395	2508
heatspreader	non noble metal	iron	7439-89-6	0.590	0.03		278	
	inorganic material	phosphorus	7723-14-0	0.177	0.01		83	
	non noble metal	copper	7440-50-8	589.466	27.74	27.78	277447	277808
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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